

DOUBLE SIDED LAPPING/POLISHING MACHINE

双面研磨/抛光机YJ-13B6L/PD

本机器主要适用于手机视窗、硅片、石英晶片、光学晶体、光学玻璃、铌酸锂、砷化镓、陶瓷片等薄脆金属或非金属的研磨或抛光。

The machine is suitable for lapping and polishing of cell phone cover lens, silicon wafer, crystal quartz, optical crystal, optical glass, lithium niobium acid, gallium arsenide, ceramic wafer and other hard and fragile metal or non-metal materials.



手机盖板



玻璃屏

设备特点

- 机器采用三电机驱动，下盘与内齿圈由同一电机驱动、上盘以及太阳轮由各单独电机驱动；在电机的驱动上、下盘作相反方向的转动，实现工件的上下磨削；
- 机器整体结构紧凑，运行平稳，有效地缩短各传动轴的长度，增加机器的机械刚度；
- 内齿圈升降采用点动操作方式，并设有限位保护，保证了升降过程的平稳、可靠；
- 电机采用变频调速器控制，能在有效设置范围内以任意速度工作、停止、加速、减速；
- 上盘装置增加机械的安全装置，在摆片、维修等状态下不会因突然故障而下降，增加了安全性；
- 太阳轮单独调速，能灵活调整工艺参数，工艺适应性强。

MAIN TECHNICAL FEATURES

- Three motors. One motor drives the lower plate and ring gear; upper plate and sun gear is controlled by separate motors.
- The length of the drive shaft is effectively shortened, mechanical rigidity of the machine is increased.
- Ring gear position is adjustable by jog operation.
- Variable frequency speed governor realizes soft start, and soft stop. Machine can work under any speed which is within setting range.
- Mechanical safety device prevents upper plate from falling down.
- Sun gear can be adjusted separately. Process craft is adjustable.

主要技术参数 MAIN TECHNICAL SPECIFICATIONS

项目/Items	规格/Specs
上、下盘尺寸(Upper, lower plate size)	柱销齿(Dowel pin tooth): $\phi 975 \times \phi 391 \times 40(35)$ mm 渐开线齿(Involute gear): $\phi 968 \times \phi 391 \times 40(35)$ mm
上盘转速(Upper plate rotational speed)	0-40 rpm
下盘转速(Lower plate rotational speed)	0-55 rpm
游星轮数量(Number of Planet gears)	6
内齿圈转速(Inner gear ring rotational speed)	0-18 r/min
上盘主气缸缸径(Upper plate main cylinder diameter)	$\phi 125$ mm
上盘主气缸行程(Upper plate cylinder stroke)	450 mm
下盘电机(Lower plate motor)	3相(phase) 7.5 kw 1450 r/min
齿圈电机(Gear ring motor)	3相(phase) 7.5 kw 1450 r/min
上盘电机(Upper plate motor)	3相(phase) 5.5 kw 1450 rpm
外形尺寸(Size L×W×H)	1685×1490×2610 mm
机器重量(Weight)	~ 2850 Kg